

## RZ/T1 Group

Independent Watchdog Timer (IWDTA)

R01AN2579EJ0140 Rev.1.40 Jun. 07, 2018

## Introduction

This application notes describes a sample program that performs reset control of the independent watchdog timer (IWDTA).

The major features of the program are listed below:

- After the IWDTA starts operating, refreshing operations are triggered at 273-ms intervals by using a compare match timer (CMT).
- Generation of a software wait in response to the external interrupt (IRQ5) stops refreshing operations, which leads to the generation of a reset. After the reset is generated, LED2 is turned on.

## **Target Devices for Operation Checking**

RZ/T1 Group

When applying the sample program covered in this application note to another microcomputer, modify the program according to the specifications for the target microcomputer and conduct an extensive evaluation of the modified program.



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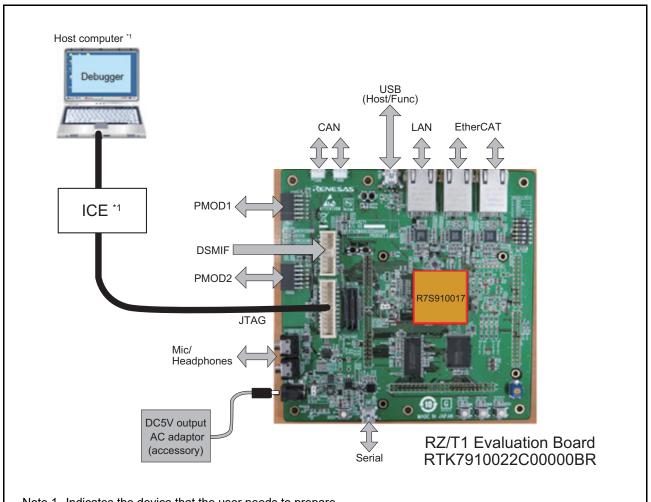
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## 1. Specifications

Table 1.1 lists the peripheral functions to be used and their applications and Figure 1.1 shows the operating environment.

Peripheral Function	Application	
Clock Pulse Generator (CPG)	The CPG produces the CPU clock and low-speed on-chip oscilla- tor clock signals	
Interrupt Control Unit A (ICUA)	The ICUA is used for the external interrupt input pin (IRQ5) and compare match timer interrupt (CMI0)	
Compare Match Timer (CMT)	The CMT is used for cycle counting of a compare match timer.	
Independent Watchdog Timer A (IWDTA)	The IWDTA operates with a timeout period of 546.1 ms and con- trol must applied to refresh its counter at regular intervals. An ECM reset is generated in response to an underflow of or error in refreshing the IWDT counter.	
Error Control Module (ECM)	The ECM is used to initialize the ERROROUT# pins and to indi- cate underflows of or errors in refreshing the IWDTA.	
General I/O port	The general I/O port is used to control pins for turning the LEDs on and off.	

 Table 1.1
 Peripheral Functions and Applications



Note 1. Indicates the device that the user needs to prepare.

Figure 1.1 Operating Environment

## 2. Operating Environment

The sample program of this application is for the environment below.

#### Table 2.1 Operating Environment

Item	Description	
Microcomputer	RZ/T1 Group	
Operating frequency	CPUCLK = 450 MHz	
Operating voltage	3.3 V	
Integrated development environment	Manufactured by IAR Systems Embedded Workbench <sup>®</sup> for Arm Version 8.20.2 Manufactured by Arm DS-5 <sup>TM</sup> 5.26.2 Manufactured by RENESAS e2studio 6.1.0	
Operating modes	SPI boot mode 16-bit bus boot mode	
Board	RZ/T1 Evaluation board (RTK7910022C00000BR)	
Devices (functions to be used on the board)	<ul> <li>NOR flash memory (connected to CS0/CS1 space) Manufacturer: Macronix International Co. Ltd. Model: MX29GL512FLT2I-10Q</li> <li>SDRAM (connected to CS2/CS3 space) Manufacturer: Integrated Silicon Solution Inc. Model: IS42S16320D-7TL</li> <li>Serial flash memory Manufacturer: Macronix International Co. Ltd. Model: MX25L51245G</li> </ul>	



## 3. Related Application Notes

Refer to the relevant application notes listed below.

- RZ/T1 Group Initial Settings
- RZ/T1 Group Compare Match Timer (CMT)



## 4. Peripheral Functions

For the basics of the clock pulse generator (CPG), independent watchdog timer (IWDTA), compare match timer (CMT), interrupt control unit A (ICUA), error control module (ECM), general input/output port, refer to the RZ/T1 Group User's Manual: Hardware.



## 5. Hardware

## 5.1 Example of Hardware Configuration

Figure 5.1 shows an example of hardware configuration.

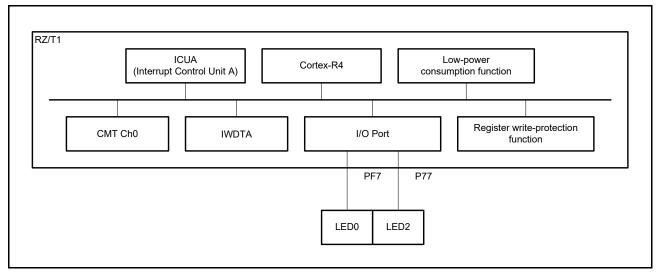


Figure 5.1 Example of Hardware Configuration

#### 5.2 Pins

 Table 5.1 shows pins to be used and their functions.

Table 5.1Pins and Pin Functions

Pin Name	I/O	Function
MD0	Input	Selection of operating modes MD0 = L, MD1 = L, MD2 = L (SPI boot mode) MD0 = L, MD1 = H, MD2 = L (16-bit bus boot mode)
MD1	Input	
MD2	Input	
IRQ5	Input	SW2 (IRQ pin interrupt)
PF7	Output	Turning LED0 on and off
P77	Output	Turning LED2 on and off

## 6. Software

## 6.1 Operation Overview

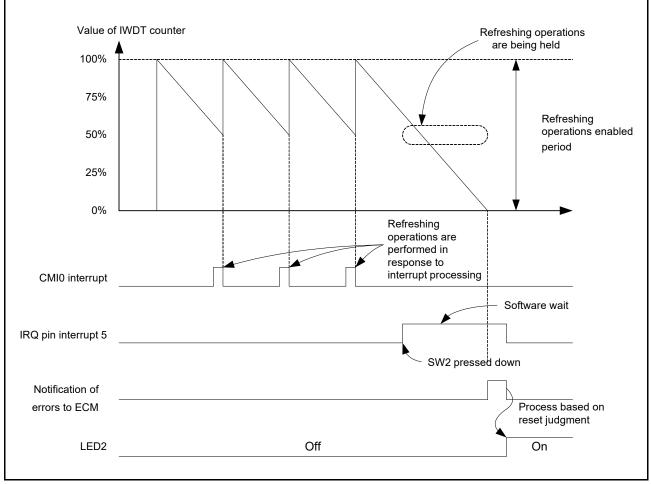
The sample program makes the initial settings of the independent watchdog timer (IWDTA), and then performs refreshing operations at regular intervals by using interval interrupts of the compare match timer.

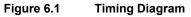
Pressing SW2 down generates an external pin interrupt 5 and a software wait proceeds during the interrupt processing. During this period, as CMT interval interrupts are held, the IWDTA stops refreshing operations. Thus, the value of the counter of the IWDTA underflows and this leads to notification of an error to the ECM and then to generation of an ECM reset. LED2 is turned on based on the reset judgment after reset release.

Table 6.1 shows the functional overview of the sample program and Figure 6.1 shows the timing diagram.

Description		
IWDTCLK/64 (= 120 kHz/64)		
1024 cycles (= 546.1 ms)		
Start: 100% End: 0%		
Enabled		

Table 6.1Functional Overview







### 6.1.1 Project Settings

For the settings of the project to be used on the EWARM for development environment, refer to the Application Note: RZ/T1 Group Initial Settings.

### 6.2 Memory Map

For the address space of the RZ/T1 Group and a memory map of the RZ/T1 evaluation board, refer to the Application Note: RZ/T1 Group Initial Settings.

#### 6.2.1 Assignment to Sections of Sample Program

Refer to the Application Note: RZ/T1 Group Initial Settings for the sections to be used in the sample program, assignment to sections (loading view) of the sample program in its initial state, and assignment to sections of the sample program following the application of scatter loading (execution view).

#### 6.2.2 MPU Settings

Refer to the Application Note: RZ/T1 Group Initial Settings for MPU settings.

#### 6.2.3 Exception Processing Vector Table

Refer to the Application Note: RZ/T1 Group Initial Settings for the vector table for exception processing.



### 6.3 Interrupts

Table 6.2 shows interrupts to be used in the sample program.

Table 6.2	Interrupts for Sample Program
-----------	-------------------------------

Interrupt (Source ID) Priority		Processing	
IRQ pin interrupt 5 (IRQ9)	0	Pressing SW2 down causes an underflow without refreshing of the IWDTA and generates an ECM reset. Based on the reset judgment after reset release, LED2 is turned on.	
Compare match interrupt_ch0 (CMI0)	15	Every time an interval period (273-ms interval) is generated, refreshing oper- ations of the IWDTA are performed.	

## 6.4 Fixed-Width Integer Types

 Table 6.3 shows fixed width integers to be used in the sample program.

int8_t8-bit signed integer (defined in the standard library)int16_t16-bit signed integer (defined in the standard library)int32_t32-bit signed integer (defined in the standard library)int64_t64-bit signed integer (defined in the standard library)uint8_t8-bit unsigned integer (defined in the standard library)uint16_t16-bit unsigned integer (defined in the standard library)uint32_t32-bit unsigned integer (defined in the standard library)uint34_t64-bit unsigned integer (defined in the standard library)uint34_t64-bit unsigned integer (defined in the standard library)uint34_t64-bit unsigned integer (defined in the standard library)	Symbol	Description
int32_t       32-bit signed integer (defined in the standard library)         int64_t       64-bit signed integer (defined in the standard library)         uint8_t       8-bit unsigned integer (defined in the standard library)         uint16_t       16-bit unsigned integer (defined in the standard library)         uint32_t       32-bit unsigned integer (defined in the standard library)	int8_t	8-bit signed integer (defined in the standard library)
int64_t       64-bit signed integer (defined in the standard library)         uint8_t       8-bit unsigned integer (defined in the standard library)         uint16_t       16-bit unsigned integer (defined in the standard library)         uint32_t       32-bit unsigned integer (defined in the standard library)	int16_t	16-bit signed integer (defined in the standard library)
uint8_t8-bit unsigned integer (defined in the standard library)uint16_t16-bit unsigned integer (defined in the standard library)uint32_t32-bit unsigned integer (defined in the standard library)	int32_t	32-bit signed integer (defined in the standard library)
uint16_t16-bit unsigned integer (defined in the standard library)uint32_t32-bit unsigned integer (defined in the standard library)	int64_t	64-bit signed integer (defined in the standard library)
uint32_t 32-bit unsigned integer (defined in the standard library)	uint8_t	8-bit unsigned integer (defined in the standard library)
	uint16_t	16-bit unsigned integer (defined in the standard library)
uint64 t 64-bit unsigned integer (defined in the standard library)	uint32_t	32-bit unsigned integer (defined in the standard library)
	uint64_t	64-bit unsigned integer (defined in the standard library)

#### 6.5 Constants/Error Codes

Table 6.4 shows constants to be used in the sample program.

#### Table 6.4 Constants for Sample Program

Constant Name	Setting Value	Description
IWDT_STAT_REFRESH_ERR_MASK	(0x8000)	A definition to acquire a refreshing error flag from the IWDT status.
IWDT_STAT_UNDERFLOW_ERR_MASK	(0x4000)	A definition to acquire an underflow flag from the IWDT status.
IWDT_STAT_ERROR_MASK	(0xC000)	A definition to acquire a refreshing error flag and underflow flag from the IWDT status.
IWDT_STAT_COUNTER_MASK	(0x3FFF)	A definition to acquire a counter value from the IWDT status.
IWDT_CFG_PARAM_CHECKING_ENABLE	(1)	The API function of IWDTA indicates enabling (1) or disabling (0) of parameter checking.

## 6.6 Structures/Unions/Enumerated Types

Figure 6.2 to Figure 6.4 show the structures, unions, and enumerated types to be used in the sample program.

```
typedef enum e_iwdt err
                           // IWDT API error codes
   IWDT SUCCESS=0,
   IWDT_ERR_OPEN_IGNORED,
                                  // The module has already been Open()ed
   IWDT_ERR_INVALID_ARG,
                                 // Argument is not valid for parameter
   IWDT_ERR_NULL_PTR,
                                 // Received null pointer or missing required argument
   IWDT_ERR_NOT_OPENED
                                   // Open function has not yet been called
} iwdt_err_t;
/* Open() DEFINITIONS */
                                      // IWDT Time-Out Period
typedef enum e_iwdt_timeout
   IWDT_TIMEOUT_1024 =0x0000u,
                                           // 1024 (cycles)
   IWDT_TIMEOUT_4096 =0x0001u,
                                          // 4096 (cycles)
   IWDT_TIMEOUT_8192 =0x0002u,
                                          // 8192 (cycles)
   IWDT_TIMEOUT_16384=0x0003u,
                                          // 16,384 (cycles)
   IWDT_NUM_TIMEOUTS
} iwdt_timeout_t;
typedef enum e_iwdt_clock_div
                                   // IWDT Clock Division Ratio
   IWDT_CLOCK_DIV_1 =0x0000u,
                                         // IWDTCLK/1
   IWDT_CLOCK_DIV_16 =0x0020u,
                                        // IWDTCLK/16
   IWDT_CLOCK_DIV_32 =0x0030u,
IWDT_CLOCK_DIV_64 =0x0040u,
                                        // IWDTCLK/32
                                       // IWDTCLK/64
   IWDT CLOCK DIV 128=0x00F0u,
                                       // IWDTCLK/128
   IWDT_CLOCK_DIV_256=0x0050u
                                       // IWDTCLK/256
} iwdt_clock_div_t;
```

Figure 6.2 Structures/Unions/Enumerated Types for Sample Program



```
// Window End Position
typedef enum e_iwdt_window_end
   IWDT_WINDOW_END_75=0x0000u,
                                            // 75%
   IWDT_WINDOW_END_50=0x0100u,
                                           // 50%
   IWDT_WINDOW_END_25=0x0200u,
                                           // 25%
   IWDT WINDOW END 0=0x0300u
                                           // 0% (window end position is not specified)
} iwdt_window_end_t;
typedef enum e_iwdt_window_start
                                       // Window Start Position
   IWDT_WINDOW_START_25 =0x0000u,
                                            // 25%
   IWDT_WINDOW_START_50 =0x1000u,
                                           // 50%
   IWDT_WINDOW_START_75 =0x2000u,
                                           // 75%
   IWDT_WINDOW_START_100=0x3000u
                                           // 100% (window start position is not specified)
} iwdt_window_start_t;
typedef enum e_iwdt_timeout_control // Signal control when Time-out and Refresh error
   IWDT ERROR ENABLE =0x00u,
                                    // Error output is enebled
   IWDT ERROR DISABLE=0x80u
                                    // Error output is disabled
} iwdt_timeout_control_t;
typedef struct st_iwdt_config
                                        /\!/ IWDT configuration options used in Open function
ł
   iwdt_timeout_t
                     timeout;
                                          // Time-out period
   iwdt_clock_div_t
                    iwdtclk_div;
                                         // IWDT clock division ratio
   iwdt_window_start_t window_start;
                                         // Window start position
                                         // Window end position
   iwdt_window_end_t window_end;
   iwdt timeout control t timeout control; // ERROR output when time-out
} iwdt_config_t;
```



/* Control() DEFINITIONS */	/* Control() DEEINITIONS */			
typedef enum e_iwdt_cmd	// Command used in Control and GetStatus function			
{				
IWDT_CMD_GET_STATUS,	// Get IWDT status			
IWDT_CMD_REFRESH_COUNTING,	// Refresh the counter			
IWDT_CMD_NO_ACTION,				
} iwdt_cmd_t;				

Figure 6.4 Structures/Unions/Enumerated Types for Sample Program



### 6.7 Functions

Table 6.5 lists functions to be used.

#### Table 6.5 Functions

Function	Page Number
main	13
iwdt_init	13
R_IWDT_Open	14
R_IWDT_Control	15
R_IRQ9_isr	15
R_IRQ21_isr	15

## 6.8 Specifications of Functions

### 6.8.1 main

#### main

Synopsis	Main processing
Declaration	int main (void)
Description	This function makes initial settings for the ports, ECM, CMT, ICU, and IWDT, and starts operation of CMT0. After that, the main loop of the function repeatedly alternates between LED0 on and off.
Arguments	None
Return value	None
Supplement	None

### 6.8.2 iwdt\_init

iwdt_init	
Synopsis	Initializing IWDT
Declaration	void iwdt_init (void)
Description	This function initializes the IWDT and starts counting operation of the IWDT.
Arguments	None
Return value	None
Supplement	None



## 6.8.3 R\_IWDT\_Open

R_IWDT_Open			
Synopsis	IWDTA open		
Header	r_iwdt_if.h		
Declaration	iwdt_err_t R_IWDT_	_Open (void * const p_cfg)	
Description	This function initializ	res IWDTA-related registers and sets the options of the IWDT counter.	
Arguments	_	This specifies the WDT channels Setting range: (0, 1)	
	. = •	The pointer that stores the data group to be set in the IWDTA-related registers	
		Timeout period IWDT_TIMEOUT_1024 IWDT_TIMEOUT_4096 IWDT_TIMEOUT_8192 IWDT_TIMEOUT_16384 Clock division ratio IWDT_CLOCK_DIV_1 IWDT_CLOCK_DIV_16 IWDT_CLOCK_DIV_32 IWDT_CLOCK_DIV_464 IWDT_CLOCK_DIV_256 Window stop IWDT_WINDOW_END_75 IWDT_WINDOW_END_50 IWDT_WINDOW_END_25 IWDT_WINDOW_END_25 IWDT_WINDOW_END_0 Window start IWDT_WINDOW_START_50 IWDT_WINDOW_START_75 IWDT_WINDOW_START_100 Notification of ECM errors IWDT_ERROR_ENABLE	
Return value	IWDT_ERROR_DISABLE Execution result of the open function IWDT_SUCCESS: IWDT initialized IWDT_ERR_OPEN_IGNORED: Module already opened		
	IWDT_ERR_INVAL	LID_ARG: Invalid values included in the element of the p_cfg structure. _PTR: p_cfg pointer null	
Supplement		_PARAM_CHECKING_ENABLE that is defined by r_iwdt_config.h to 1 the parameters of the arguments.	



## 6.8.4 R\_IWDT\_Control

_	 -
R	Contro
· ' \_	

IVDI_Control		
Synopsis	Controlling IWDTA	
Header	r_iwdt_if.h	
Declaration	iwdt_err_t R_IWDT_Co	ontrol (iwdt_cmd_t const cmd, uint16_t * p_status)
Description	This function reads the	state of the IWDT and refreshes the down counter of the IWDT.
Arguments	iwdt_cmd_t const cmd	Specifies the command to be executed IWDT_CMD_GET_STATUS IWDT_CMD_REFRESH_COUNTING
	uint16_t * p_status	The pointer to the storage positions of the counter and status flag
Return value	Execution result of the IWDT_SUCCESS: Co IWDT_ERR_INVALID IWDT_ERR_NULL_P IWDT_ERR_NOT_OF	ommand completed _ARG: Argument value invalid TR: p_status null.
Supplement	• = =	ARAM_CHECKING_ENABLE that is defined by r_iwdt_config.h to 1 e parameters of the argument.

## 6.8.5 R\_IRQ9\_isr

R_IRQ9_isr	
Synopsis	IRQ9 interrupt (IRQ pin interrupt 5) processing
Declaration	void R_IRQ9_isr (void)
Description	This function executes software wait processing (approx. 3 seconds). During this period, it causes an underflow of the independent watchdog timer and generates an ECM reset. It also turns LED2 on based on the reset judgment after reset release.
Arguments	None
Return value	None
Supplement	None

## 6.8.6 R\_IRQ21\_isr

R_IRQ21_isr	R_IRQ21_isr			
Synopsis	IRQ21 interrupt (compare match timer (CMI0)) processing			
Declaration	void R_IRQ21_isr (void)			
Description	This functions performs refreshing operations of the independent watchdog timer.			
Arguments	None			
Return value	None			
Supplement	None			



## 6.9 Flowcharts

### 6.9.1 Main Processing

Figure 6.5 shows a flowchart of main processing.

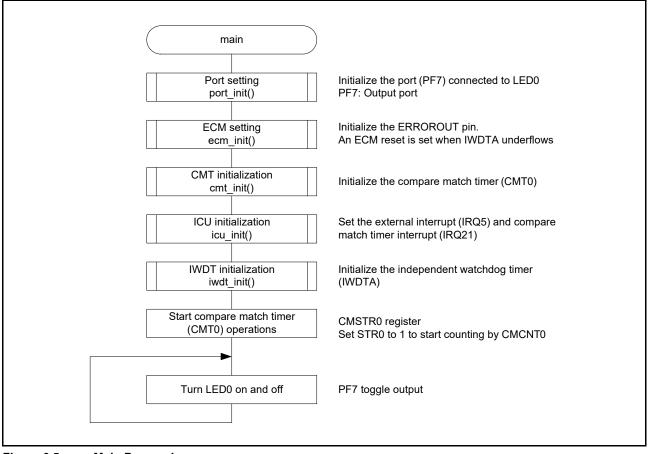


Figure 6.5 Main Processing



## 6.9.2 IWDT Initialization

Figure 6.6 show a flowchart of IWDT initialization.

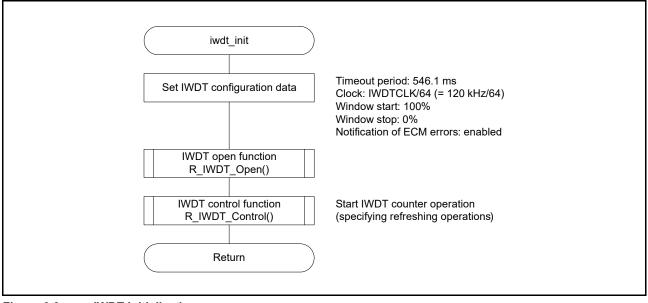
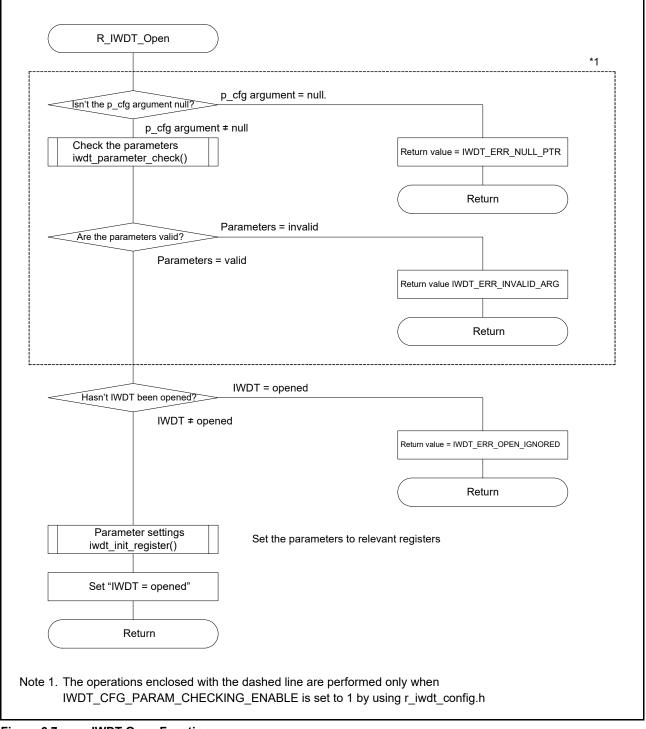


Figure 6.6 IWDT Initialization



## 6.9.3 IWDT Open Function

Figure 6.7 shows a flowchart of IWDT open function.

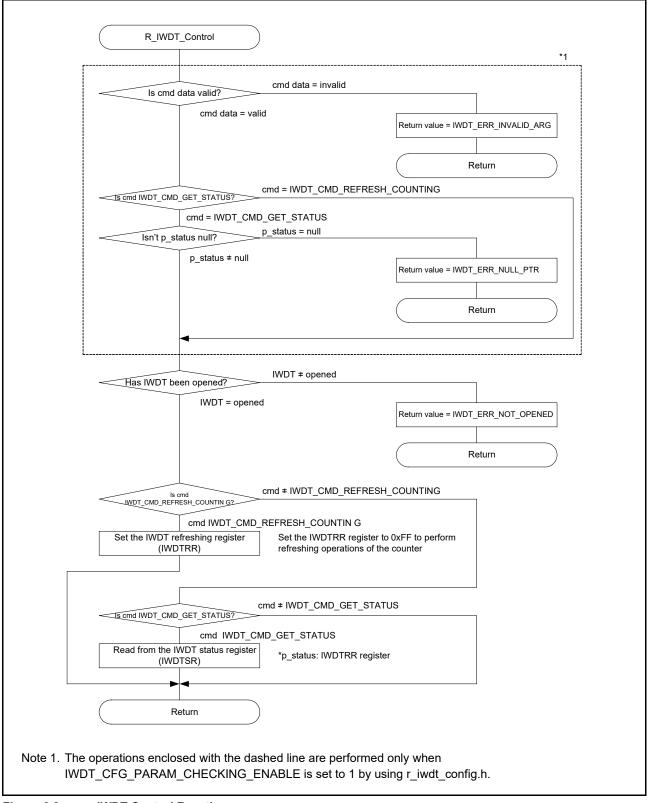






## 6.9.4 IWDT Control Function

Figure 6.8 shows a flowchart of the IWDT control function.





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## 6.9.5 IRQ9 Interrupt (IRQ Pin Interrupt 5) Processing

Figure 6.9 shows a flowchart of the IRQ9 interrupt (IRQ pin interrupt 5) processing.

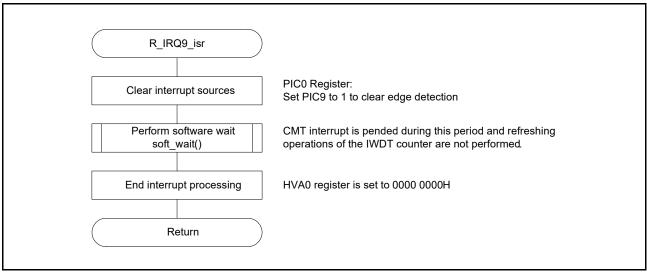


Figure 6.9 IRQ9 Interrupt (IRQ Pin Interrupt 5) Processing

## 6.9.6 IRQ21 Interrupt (Compare Match Timer Ch0 Interrupt) Processing

Figure 6.10 shows a flowchart of IRQ21 interrupt (compare match timer ch0 interrupt) processing.

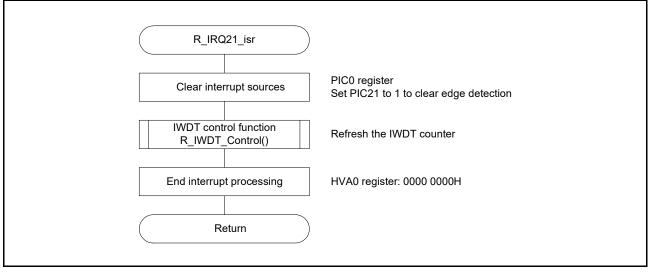


Figure 6.10 IRQ21 Interrupt (Compare Match Timer ch0 Interrupt) Processing



# 7. Sample Program

The sample program is available on the Renesas Electronics website.



## 8. Reference Documents

User's manual: hardware:

RZ/T1 Group User's Manual: Hardware

(Download the latest version of the manual from the Renesas Electronics website.)

RZ/T1 Evaluation Board RTK7910022C00000BR User's Manual (Download the latest version of the manual from the Renesas Electronics website.)

Technical Update / Technical News (Download the latest version of the update or news from the Renesas Electronics website.)

User's manual: Development Environment

For IAR integrated development environment (IAR Embedded Workbench<sup>®</sup> for Arm), visit the IAR Systems website. (Download the latest version from the IAR Systems website.)



# Website and Support

Renesas Electronics website

http://www.renesas.com/

Inquiries

http://www.renesas.com/inquiry



## Application Note: Independent Watchdog Timer (IWDTA)

NumPageSummary0.20Mar. 18, 2015—First Edition issued1.00Apr. 10, 2015—Only the revision number was changed to be posted on a website.1.10Aug. 18, 20152. Operating Environment1.10Aug. 18, 20152. Operating Environment: Integrated Development Environment, partially amended and added6. Software96.2.4 Required Memory Size: Description and reference added97able 6.2: Table title was partially amended1.20Dec. 04, 20152. Operating Environment1.30Apr. 05, 20172. Operating Environment1.30Apr. 05, 20172. Operating Environment1.40Jun. 07, 20182. Operating Environment: Integrated Development Environment, modified1.40Jun. 07, 20182. Operating Environment	Davi	Date	Description		
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#### General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.
- 2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at
- which resetting has been specified.3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access
  these addresses; the correct operation of LSI is not guaranteed if they are accessed.
- 4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal.
   Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.
- 5. Differences between Products

Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

— The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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